

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 10/789,799
Applicant : KUO, Frank
Filed : February 27, 2004
T.C./A.U. : 1732
Examiner : LEE, Edmund

Title : Encapsulation Method and Leadframe for Leadless Semiconductor
Packages
Docket No. : VISH-4123.DIV

Confirmation No. : 9449

AMENDMENT AND RESPONSE TO OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action of January 3, 2007, Applicant respectfully requests further examination and reconsideration of the above-identified patent application in view of the arguments set forth below.